

AMENDMENT E
(37 CFR 1.111)

IN THE CLAIMS:

Please cancel Claim 24 without disclaimer to its content and without prejudice to its subsequent reintroduction into this or a future patent application.

Please amend Claims 23 and 29. The status of the claims, as amended, are attached on separate sheets.

CLAIMS

1-22. (Previously canceled)

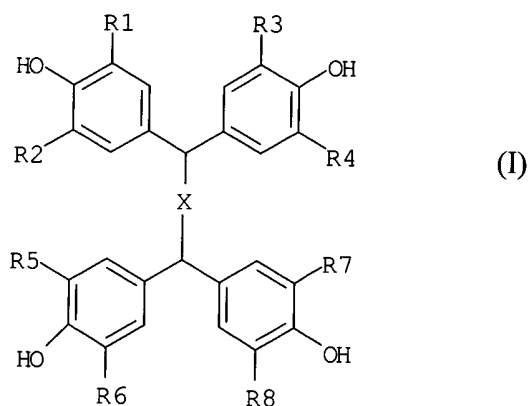
23. (Currently Amended) An epoxy resin composition comprising:

~~a non-curing~~ an epoxy resin prior to curing,

a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin, and

a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst,

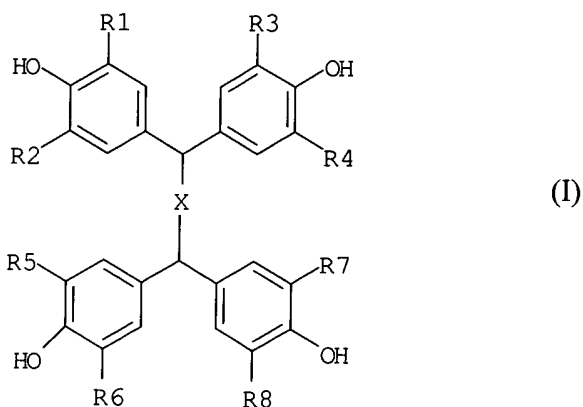
wherein the content of said tetrakisphenol compound ranges from 0.001 to 0.1 mole based on 1 mole of the epoxy group,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

24. (Canceled)

25. (Previously added and withdrawn due to restriction requirement) A method for curing an epoxy resin comprising a step of mixing a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst with a non-curing epoxy resin,

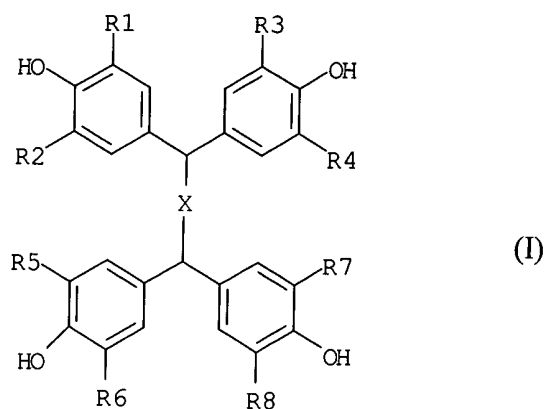


wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

26. (Previously added and withdrawn due to restriction requirement) The method for curing an epoxy resin according to claim 25, wherein the content of the tetrakisphenol compound represented in general formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

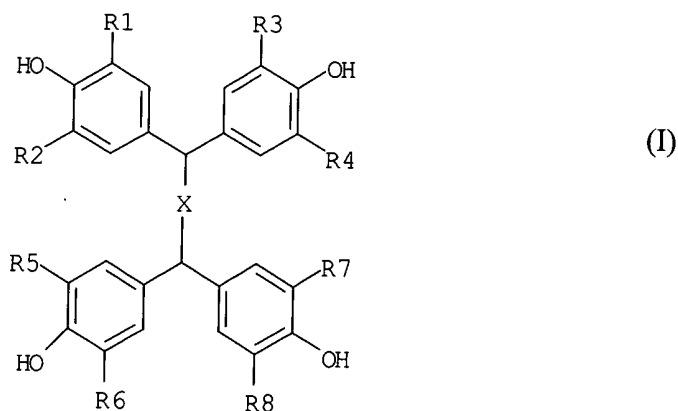
27. (Previously added and withdrawn due to restriction requirement) A curative for epoxy resin, comprising a clathrate comprising:

a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group to cure an epoxy resin,



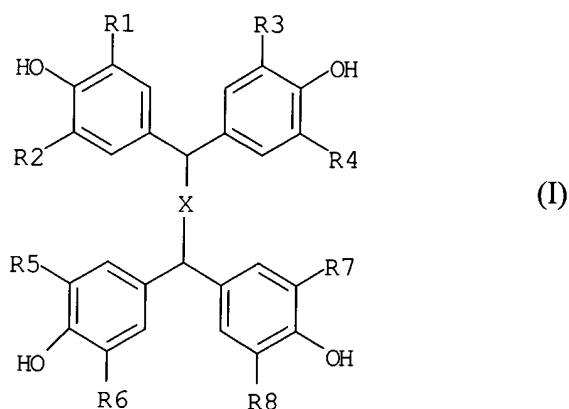
wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

28. (Previously added and withdrawn due to restriction requirement) A curing accelerator for epoxy resin, comprising a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

29. (Currently Amended) An epoxy resin composition, comprising ~~a non-~~
euring an epoxy resin **prior to curing**, and a clathrate comprising a tetrakisphenol compound
 represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy
 resin to cure the resin,

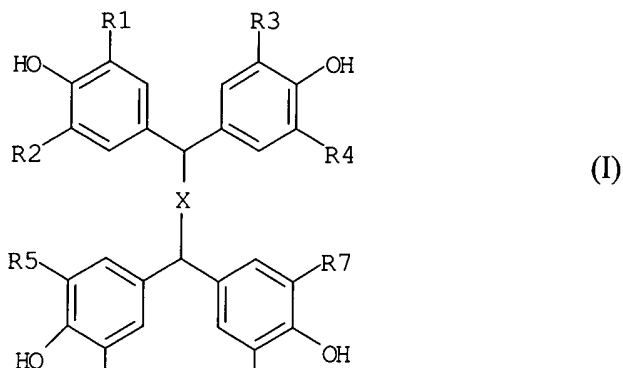


wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

30. (Previously added and withdrawn due to restriction requirement) An epoxy
 resin composition comprising a non-curing epoxy resin, and

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin; and

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,

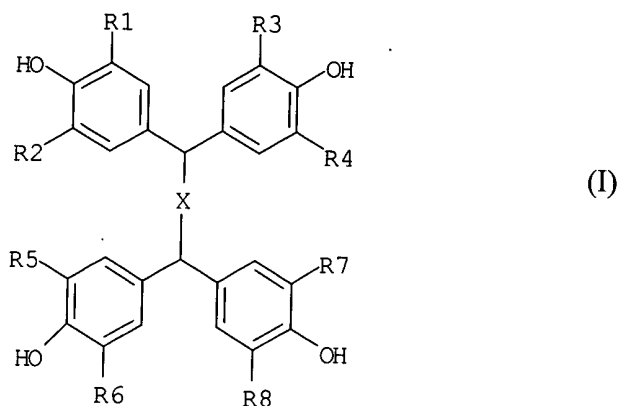


wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

31. (Previously added and withdrawn due to restriction requirement) The epoxy resin composition according to claim 29 or 30, wherein the content of a tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

32. (Previously added and withdrawn due to restriction requirement) A method for curing an epoxy resin composition comprising the steps of:

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin is added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,

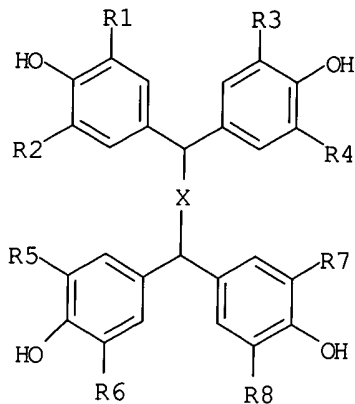


wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

33. (Previously added and withdrawn due to restriction requirement) A method for curing an epoxy resin composition comprising the steps of:

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin, and

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin are added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,



(I)

wherein X represents (CH₂)_n, wherein n is 0, 1, 2 or 3, and R¹ to R⁸ each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C₁-C₆ alkyl, a halogen or a C₁-C₆ alkoxy.

34. (Previously added and withdrawn due to restriction requirement) The method for curing an epoxy resin composition according to claim 32 or 33, wherein the content of the tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.